

Title (en)  
CONTINUOUS CASTING MOLD AND METHOD FOR CONTINUOUS CASTING OF STEEL

Title (de)  
STRANGGUSSFORM UND VERFAHREN ZUM STRANGGIESSEN VON STAHL

Title (fr)  
MOULE DE MOULAGE CONTINU ET PROCÉDÉ DE MOULAGE CONTINU D'ACIER

Publication  
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Application  
**EP 20206258 A 20170116**

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Abstract (en)  
[origin: EP3488946A1] A surface crack due to the inhomogeneous cooling of a solidified shell in the early solidification stage and a surface crack due to a variation in the thickness of a solidified shell caused by transformation from  $\delta$  iron to  $\gamma$  iron in medium-carbon steel are inhibited. A continuous casting mold includes portions filled with a metal of low thermal conductivity formed by filling a plurality of concave grooves with the metal of low thermal conductivity in a region, on an inner wall surface of a mold copper plate which is made of a copper alloy and constitutes a water-cooled continuous casting mold, from a position located above a meniscus to a position located below the meniscus, in which a ratio of a thermal conductivity  $\lambda(W/(m \times K))$  of the metal of low thermal conductivity to a thermal conductivity  $\lambda(W/(m \times K))$  of the mold copper plate is 80% or less, and in which a thermal resistance ratio R defined by expression (1) below is 5% or more. Here, R denotes a thermal resistance ratio (%) of the portions filled with the metal of low thermal conductivity to the mold copper plate, T denotes a distance (mm) from a bottom surface of a slit of the mold copper plate, which is used as a flow channel of mold-cooling water, to a surface of the mold copper plate, and H denotes a filling thickness (mm) of the metal of low thermal conductivity.

IPC 8 full level  
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